

AMENDMENTS TO THE CLAIMS

This Listing of Claims will replace all prior versions, listing, of claims in the specification.

LISTING OF CLAIMS:

Claims 1-7 (canceled).

Claim 8 (original) The usage of copper/copper alloy surface bonding promotor comprising the steps of:

- a) providing a circuit board having a copper/copper alloy surface;
- b) microetching said copper/copper alloy surface with an etchant containing chloride ions/ferrite ions; and
- c) roughening the etched copper/copper alloy surface with a surface bonding promotor, which comprises copper oxidant 0.1~20wt%, acidic solution without halogen ion and hydrogen peroxide 5~20wt%, and nonionic compound having amino/CONH chains 0.001~10wt%.

Claim 9 (original) The usage of a copper/copper alloy surface bonding promotor as claimed in claim 8, wherein said microetching is achieved by means of spraying/immersion.

Claim 10 (original) The usage of a copper/copper alloy surface bonding promotor as claimed in claim 8, wherein the process of roughening the etched copper/copper alloy surface with a surface bonding promotor is preferably performed at temperature range within 20~40°C.

Claim 11 (original) The usage of a copper/copper alloy surface bonding promotor as claimed in claim 8, wherein said acidic solution is selected from organic acid, inorganic acid, and their mixture.

Claim 12 (original) The usage of a copper/copper alloy surface bonding promotor as claimed in claim 8, wherein said copper oxidant is selected from potassium peroxodisulfate, sodium persulfate, potassium persulfate, copper sulfate, copper oxide, copper carbonate, and their mixture.

Claim 13 (original) The usage of a copper/copper alloy surface bonding promotor as claimed in claim 8, wherein said nonionic compound is a surfactant soluble to water.

Claim 14 (original) The usage of a copper/copper alloy surface bonding promotor as claimed in claim 11, wherein said organic acid is selected from the acidic group of unsaturated fatty acid and methyl Amidosulfuric Acid .

Claim 15 (original) The usage of a copper/copper alloy surface bonding promotor as claimed in claim 11, wherein said inorganic acid is selected from the acidic group of sulfuric acid, nitric acid, phosphoric acid, and Amidosulfuric Acid.